Ref #	Hits	Search Query	DBs	Default Operator	Plurals	·Time Stamp
L1	84	substrate same via same chip and bonding with wire and heat same spreader and ground with heat	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/06/21 16:00
L2	1	("6703698").PN.	USPAT	OR	OFF	2005/06/21 16:00